an insulating shroud that lines an interior of said chamber, said insulating shroud being configured to be electrically floating during said processing; and

a perforated plasma confinement ring **surrounding and** disposed outside of an outer periphery of said bottom electrode, **[a top surface of]** said perforated plasma confinement ring being disposed **in its entirety at or** below a top surface of said substrate, said perforated plasma confinement ring being formed from **an electrically** conductive material and electrically grounded during said processing so as to increase ion energy during said processing **by removing electrons from said plasma.**

C2 ~~24.~~ 23' A perforated plasma confinement ring **[device configured to be disposed] for confining a plasma** inside a **process chamber of a** plasma **[processing]** reactor during processing **of a substrate, the process chamber having a liner with either an electrically insulating material or a material that is electrically floating, the perforated plasma confinement ring** comprising:

a conductive ring having an inner **surface [and outer diameter, said inner diameter being]** dimensioned to surround a bottom electrode disposed in said **process chamber and a top surface arranged to be substantially parallel with a top surface of said bottom electrode when said conductive ring is surrounding said bottom electrode [plasma processing reactor, said bottom electrode providing support for a substrate to be processed, said bottom electrode being coupled to a first RF source having a first RF frequency, said bottom electrode being spaced apart from a top electrode, said top electrode being coupled to a second RF source having a second RF frequency, said second RF frequency being greater than said first RF frequency,]** said conductive ring being formed from **an electrically conductive material [a conductor]** that is substantially resistant to etching by said plasma present within said chamber during said processing, said conductive ring being electrically grounded during said processing, said conductive ring having therein a plurality of perforations, said plurality of perforations being dimensioned to permit by-product gases from said processing to pass through while substantially confining a plasma to the upstream side of said conductive ring, and said conductive ring removing electrons from said plasma and thereby increasing ion energy in said plasma.

C3 ~~35.~~ 33 A perforated plasma confinement ring for containing a plasma inside a process chamber of a plasma **[processing]** reactor during processing of a substrate, the **[perforated confinement ring being disposed between] plasma reactor** including a bottom electrode and a side wall

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